

修订记录 / Revised record

A	2020.08.21		LRC-LMUN5314DW1T1G		
B	2021-11-25	6			

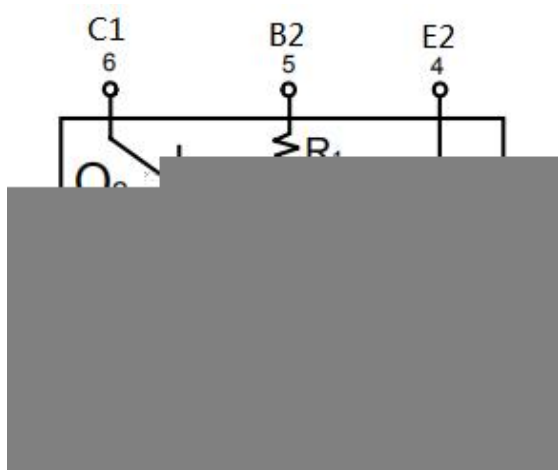
描述 / Descrip

SOT-363 NPN+PNP

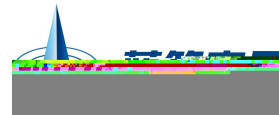
Double silicon NPN and PNP transistor in a SOT-363 Plastic Package

With built-in bias resistors, simplify circuit design, reduce a quantity of parts and manufacturing process, Halogen-free Product.

Switching applications, interface circuit and driver circuit applications.

**放大及印章代码 / h_{FE} Classifications & Marking**

Marking	H314
---------	------



Parameter	Symbol	Rating	Unit
Output Voltage	V_{CC}	50	V
Input Voltage	V_{IN}	40	V
		-6	V
Output Current	I_C	100	mA
	I_O	70	mA
Power Dissipation	P_C	200	mW
Junction Temperature	T_j	150	°C
Storage Temperature Range	T_{stg}	-55~150	°C

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Input Voltage(OFF)	$V_{I(off)}$	$V_{CC}=5.0V$ $I_O=100\mu A$			0.3	V
Input Voltage(ON)	$V_{I(on)}$	$V_O=0.3V$ $I_O=1mA$	1.4			V
Output Voltage	$V_{O(on)}$	$I_O=5mA$ $I_I=0.25mA$		0.1	0.3	V

I

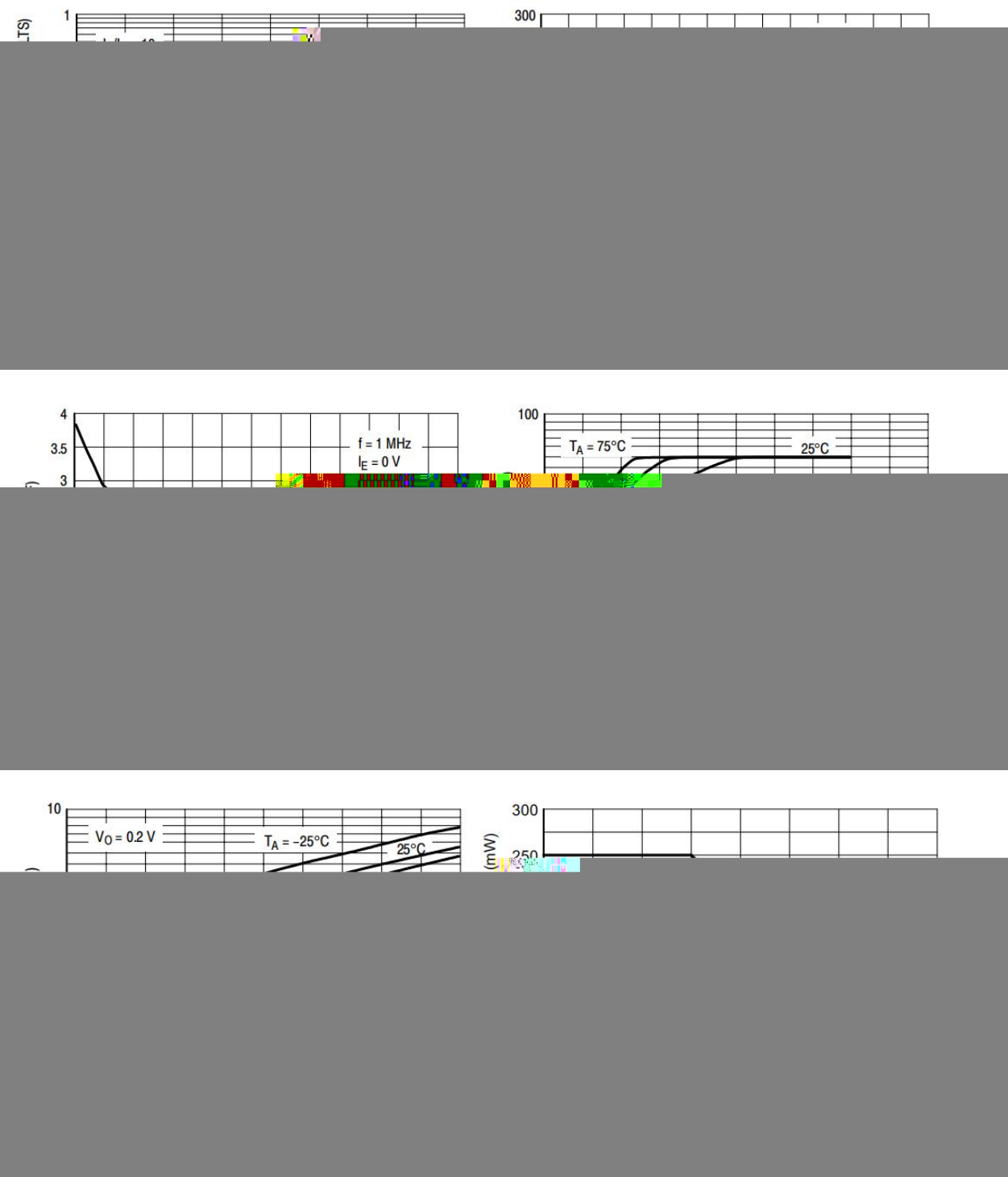
/



Parameter	Symbol	Rating	Unit
Output Voltage	V_{CC}	-50	V
Input Voltage	V_{IN}	-40	V
		6.0	V
Output Current	I_C	-100	mA
	I_O	-70	mA
Power Dissipation	P_C	200	mW
Junction Temperature	T_j	150	°C
Storage Temperature Range	T_{stg}	-55~150	°C

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Input Voltage(OFF)	$V_{I(off)}$	$V_{CC}=-5.0V$ $I_O=-100\mu A$			-0.3	V
Input Voltage(ON)	$V_{I(on)}$	$V_O=-0.3V$ $I_O=-1.0mA$	-1.4			V

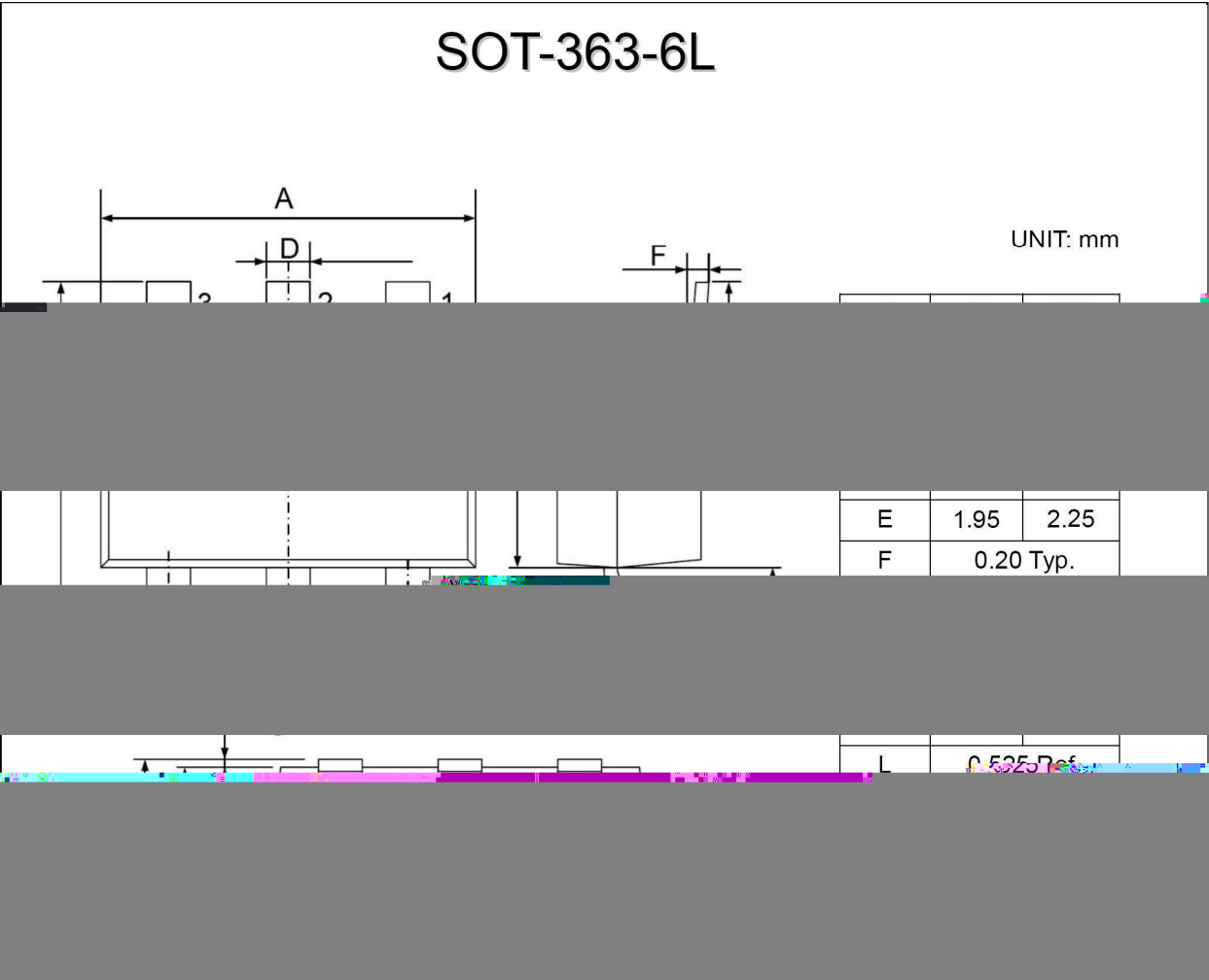
电参数曲线图 / Electrical Characteristic Curve(NPN)

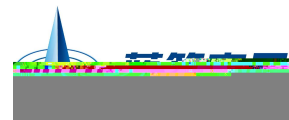


BRMUN5314WS

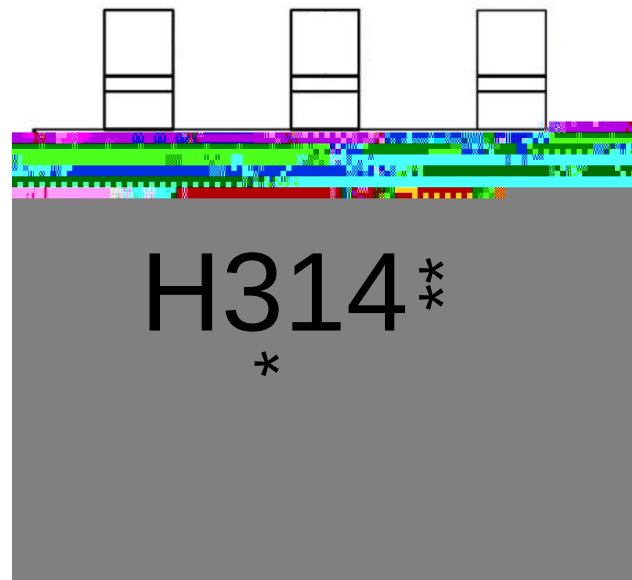
Rev.B Nov.-2021

外形尺寸图 / Package Dimensions





印章说明 / Marking Instructions



" 1 "

H314

***:

Note:



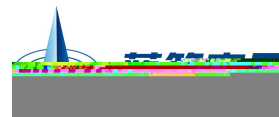
"1" Pin

H314

Product Type Code

***:

Lot No. Code, code change with Lot No.



回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)

Note:

- | | | | |
|---|---------|-----------|--|
| 1 | 150 180 | 60 90sec; | 1.Preheating:150~180°C, Time:60~90sec. |
| 2 | 245±5 | 5±0.5sec; | 2.Peak Temp.:245±5°C, Duration:5±0.5sec. |
| 3 | 2 | 10°C/sec. | 3. Cooling Speed: 2~10°C/sec. |

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

260±5°C	10±1 sec.	Temp.:260±5°C	Time:10±1 sec
---------	-----------	---------------	---------------

包装规格 / Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱 U